

EAST Search History

EAST Search History (Prior Art)

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|--------|--|---|------------------|---------|---------------------|
| L1 | 26595 | ((("3" or third or "3rd" or additional or another or extra or supporting or supportive) near3 (layer or lamina or level or coating or coated or coat or ply or overlay or sheet or zone)) and (semiconductor or semiconductive or semi conductor or semi?conductor or semi-sonductor) and (polymer or pmma or polymethylmethacry\$ or poly?methylmethacry\$ or poly methylmethacry\$ or polymethyl methacryl\$ or poly-methylmethacryl \$ or poly?methyl methacryl\$) and (template or stamp or stamper or press or pattern or imprint or imprinting or inprinted) and (nanometer or nm or nano-meter or nano?meter) | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/10/01 11:18 |
| L9 | 1 | ("6849558").PN. | US-PGPUB; USPAT; USOCR | OR | OFF | 2009/10/01 11:48 |
| L10 | 250124 | anneal or anneal\$ | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/10/01 12:29 |
| L11 | 8424 | L10 near (polymer or plastic or template or semiconductor or mold) | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/10/01 12:29 |
| L12 | 278 | L11 and ("264".clas. or "425".clas.) | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/10/01 12:29 |
| L13 | 4689 | ((425/171) or (425/174) or (425/174.4) or (264/1.38) or (425/385) or (425/169) or (425/173)).CCLS. | US-PGPUB; USPAT; USOCR | OR | OFF | 2009/10/01 12:29 |
| L14 | 3945 | (ge or germanium) near semiconductor | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2009/10/01 12:30 |
| L15 | 145874 | semiconductor adj layer | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2009/10/01 12:30 |
| L16 | 942303 | nm or nanometer or nanoprint or nanoimprint or nanopattern | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2009/10/01 12:30 |

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|-----|--------|---|---|-----|-----|---------------------|
| L17 | 235313 | silicon near substrate | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2009/10/01 12:30 |
| L18 | 398 | L14 and L15 and L17 and L16 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2009/10/01 12:30 |
| L19 | 34 | ((SHUNPU) near2 (LI)).INV. | EPO; JPO; DERWENT | ADJ | ON | 2009/10/01 12:30 |
| L20 | 202371 | @AD> "20090513" or @pds> "20090512" or @prads> "20090513" | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/10/01 12:33 |
| L21 | 82 | (18 or 19 or 13 or 12) and 20 | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/10/01 12:34 |
| S1 | 2 | ("5948470").PN. or ((2002/042027 or (2002/005391)).CCLS. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/05/19 12:45 |
| S2 | 0 | (2002/042027).CCLS. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/05/19 13:35 |
| S3 | 0 | 2002/042027 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/19 13:35 |
| S4 | 0 | 2002/042027 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/19 13:36 |
| S5 | 0 | (stephen chou).inv. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/19 13:36 |
| S6 | 4 | ("2002042027").PN. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/05/19 13:37 |

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| S7 | 89 | (stephen near chou).inv. | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/19 13:43 |
| S8 | 0 | S7 and @pd="02200411" | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/19 13:44 |
| S9 | 0 | (2002/0005391).CCLS | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/05/19 13:46 |
| SI0 | 0 | (2002/005391).CCLS | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/05/19 13:46 |
| SI1 | 0 | 2002/005391 | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/19 13:46 |
| SI2 | 0 | 2002/0005391 | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/19 13:47 |
| SI3 | 0 | thurn-albrect.inv. | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/19 13:47 |
| SI4 | 10 | (thurn-albrecht).inv. | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/19 13:48 |
| SI5 | 75 | "5948470" | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/19 13:50 |

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| SI6 | 2 | ("5948470").PN. | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/05/19 13:50 |
| SI7 | 0 | (wo01/33300).OCL. | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/05/19 13:50 |
| SI8 | 20 | 01/33300 | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/19 13:51 |
| SI9 | 0 | ("wo20010500").PN. | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/05/19 13:52 |
| S20 | 117005 | "20010500" | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/19 13:53 |
| S21 | 0 | wo?20010500 | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/19 13:53 |
| S22 | 0 | wo20010500 | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/19 13:53 |
| S23 | 2 | ("7082876").PN. | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/05/19 13:54 |
| S24 | 0 | WO "20010500" | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/19 14:26 |

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| S25 | 0 | method of reducing pattern distortions during imprint lithography | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/19 14:30 |
| S26 | 15 | reducing pattern distortions during imprint lithography | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/19 14:31 |
| S27 | 1 | wo-0133300-\$.did. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/19 14:32 |
| S28 | 2 | de-10030016-\$.did. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/19 14:34 |
| S29 | 32985954 | @pd<"20031112" | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 10:04 |
| S30 | 1308003 | template or mold | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 10:05 |
| S31 | 7481 | S30 near substrate | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 10:06 |
| S32 | 289533 | silicon near3 substrate | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 10:06 |
| S33 | 436 | S31 with (polymer or pmma or pmgi or photoresist) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 10:07 |

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| S34 | 168 | S29 and S30 and S33 | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 10:07 |
| S35 | 798153 | nanometer or nm or nanoprnt or nanopattern | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 10:09 |
| S36 | 48 | S34 and S35 | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 10:09 |
| S37 | 28 | S29 and S33 and S32 and S35 | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 10:14 |
| S38 | 3465 | (ge or germanium) near semiconductor | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 13:06 |
| S39 | 126033 | semiconductor adj layer | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 13:06 |
| S40 | 207948 | silicon near substrate | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 13:07 |
| S41 | 798313 | nm or nanometer or nanoprnt or nanoinprint or nanopattern | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 13:08 |
| S42 | 32985954 | @pd< "20031112" | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 13:09 |

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| S43 | 3465 | (ge or germanium) near semiconductor | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 13:11 |
| S44 | 126033 | semiconductor adj layer | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 13:11 |
| S45 | 798313 | nm or nanometer or nanoprint or nanoimprint or nanopattern | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 13:11 |
| S46 | 0 | S43 and S44 and s "40" and S45 | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 13:11 |
| S47 | 207948 | silicon near substrate | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 13:11 |
| S48 | 322 | S43 and S44 and S47 and S45 | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 13:11 |
| S49 | 32985954 | @pd<"20031112" | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 13:12 |
| S50 | 93 | S48 and S49 | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 13:12 |
| S51 | 28 | S50 and (pmma or polymer or photoresist or pmgi) | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 13:13 |

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| S52 | 226110 | template | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 14:32 |
| S53 | 55209 | S52 and "43" and "45" and "51" | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 14:33 |
| S54 | 3465 | (ge or germanium) near semiconductor | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 14:34 |
| S55 | 126033 | semiconductor adj layer | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 14:34 |
| S56 | 798313 | nm or nanometer or nanoprnt or nanoimprint or nanopattern | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 14:34 |
| S57 | 207948 | silicon near substrate | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 14:34 |
| S58 | 322 | S54 and S55 and S57 and S56 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 14:34 |
| S59 | 32985954 | @pd<"20031112" | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 14:34 |
| S60 | 93 | S58 and S59 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 14:34 |

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| S61 | 28 | S60 and (pmma or polymer or photoresist or pmgi) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 14:34 |
| S62 | 0 | S52 and S54 and S56 and S61 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 14:34 |
| S63 | 463 | (silicon near substrate) and (polymer or pmma or pmgi or photoresist) and (semiconductor near (ge or germanium)) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 14:36 |
| S64 | 159 | S63 and S59 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 14:37 |
| S65 | 13 | S60 and (pmma or polymer or pmgi) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 14:47 |
| S66 | 346 | S59 and S56 and S52 and S57 and germanium | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/05/20 14:48 |
| S67 | 4630 | ((((nano?imprint\$3) or (nano imprint \$3) or (imprint adj lithograp\$6) or nanolithograp\$5 or (nano?lithogra \$6)) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 10:34 |
| S68 | 1602236 | germanium or ge | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 10:35 |
| S69 | 268466 | (pmma or polymethylmeth\$ or pmgi or polymethylgluta\$ or az5214e or photoresist) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 10:38 |

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| S70 | 1112 | S67 and S68 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 10:38 |
| S71 | 101 | S67 same S68 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 10:38 |
| S72 | 1540 | S67 and S69 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 10:41 |
| S73 | 480 | S67 same S69 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 10:42 |
| S74 | 26586 | S68 and S69 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 10:42 |
| S75 | 3507 | S68 same S69 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 10:42 |
| S76 | 10 | S71 and S73 and S75 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 10:42 |
| S77 | 65 | shunpu.inv. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 11:21 |
| S78 | 19543 | template.ti. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 11:21 |

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| S79 | 4 | S78 and S77 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 11:21 |
| S80 | 3 | ("4407695" "4512848" "4801476").PN. | US-PGPUB; USPAT; USOCR | ADJ | ON | 2008/07/21 12:38 |
| S81 | 34806 | germanium with (aluminum or al or indium or gold) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 14:15 |
| S82 | 5375 | (germanium with (aluminum or al or indium or gold)) with semiconductor | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 14:16 |
| S83 | 30322507 | @ad< "20050513" | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 14:20 |
| S84 | 3671 | S82 and S83 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 14:20 |
| S85 | 92 | S84 and substrate and pmma | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 14:20 |
| S86 | 505 | ((((germanium with (aluminum or al or indium or gold)) with semiconductor) with substrate) and S69 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 14:31 |
| S87 | 938302 | "427".clas. or "428".clas. or "430". clas. or "425".clas. or "264".clas. or "156".clas. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 14:35 |
| S88 | 572282 | S83 and S87 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 14:36 |

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| S89 | 2 | ("4512848").PN. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/07/21 14:41 |
| S90 | 483 | photoresist and template and silicon and germanium and S69 and pattern and (nanometer or angstrom or nm) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 15:03 |
| S91 | 108 | S90 and S88 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 15:04 |
| S92 | 108 | S91 and germanium | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 15:13 |
| S93 | 268466 | (pmma or polymethylmeth\$ or pmgi or polymethylgluta\$ or az5214e or photoresist) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 17:12 |
| S94 | 30322507 | @ad< "20050513" | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 17:12 |
| S95 | 938302 | "427".clas. or "428".clas. or "430".clas. or "425".clas. or "264".clas. or "156".clas. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 17:12 |
| S96 | 572282 | S94 and S95 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 17:12 |
| S97 | 483 | photoresist and template and silicon and germanium and S93 and pattern and (nanometer or angstrom or nm) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 17:12 |

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| S98 | 108 | S97 and S96 | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 17:12 |
| S99 | 108 | S98 and germanium | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 17:12 |
| Si00 | 34 | S99 and (imprint with lithography) | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 17:12 |
| Si01 | 34 | (US-20060076717-\$ or US-20060062867-\$ or US-20060035164-\$ or US-20040141168-\$ or US-20040124566-\$ or US-20040086793-\$ or US-20040053146-\$ or US-20040022888-\$ or US-20040021254-\$ or US-20040007799-\$ or US-20030205658-\$ or US-20030205657-\$ or US-20020115002-\$ or US-20020098426-\$ or US-20020094496-\$ or US-20020093122-\$).did. or (US-7374968-\$ or US-7338275-\$ or US-7229273-\$ or US-7179079-\$ or US-7140861-\$ or US-7132225-\$ or US-7077992-\$ or US-7070405-\$ or US-7037639-\$ or US-7027156-\$ or US-6954275-\$ or US-6932934-\$ or US-6926921-\$ or US-6921615-\$ or US-6919152-\$ or US-6916585-\$ or US-6916584-\$ or US-6696220-\$).did. | US-PGPUB; USPAT | ADJ | ON | 2008/07/21 17:28 |
| Si02 | 34 | Si01 and germanium | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 17:29 |
| Si03 | 1 | Si02 not (silicon adj germanium) | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 17:31 |

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| S104 | 1 | S103 and germanium and S93 and S97 | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/21 17:35 |
| S105 | 13 | ("20030213382" "20040163758" "5512131" "6060121" "6365059" "6407443" "6518194" "6547940" "6599824" "6709929" "6755984" "6764833" "7060625").PN. | US-PGPUB; USPAT: USOCR | ADJ | ON | 2008/07/22 07:59 |
| S106 | 5 | "6506660" | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/22 08:08 |
| S107 | 34 | (US-20060076717-\$ or US- 20060062867-\$ or US- 20060035164-\$ or US- 20040141168-\$ or US- 20040124566-\$ or US- 20040086793-\$ or US- 20040053146-\$ or US- 20040022888-\$ or US- 20040021254-\$ or US- 20040007799-\$ or US- 20030205658-\$ or US- 20030205657-\$ or US- 20020115002-\$ or US- 20020098426-\$ or US- 20020094496-\$ or US- 20020093122-\$).did. or (US- 7374968-\$ or US-7338275-\$ or US- 7229273-\$ or US-7179079-\$ or US- 7140861-\$ or US-7132225-\$ or US- 7077992-\$ or US-7070405-\$ or US- 7037639-\$ or US-7027156-\$ or US- 6954275-\$ or US-6932934-\$ or US- 6926921-\$ or US-6921615-\$ or US- 6919152-\$ or US-6916585-\$ or US- 6916584-\$ or US-6696220-\$).did. | US-PGPUB; USPAT | ADJ | ON | 2008/07/22 09:59 |
| S108 | 34 | S107 and germanium | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/22 09:59 |
| S109 | 1666 | germanium with sputter\$4 | US-PGPUB; USPAT: USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/22 10:17 |

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|------|----|--|---|-----|----|---------------------|
| SI10 | 26 | SI09 and silicon and pmma | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/22 10:17 |
| SI11 | 34 | SI07 and nm | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/22 12:33 |
| SI12 | 16 | SI07 and ((layer with nm) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/22 12:34 |
| SI13 | 7 | SI07 and ((thick or thickness) with nm) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/22 12:37 |
| SI14 | 0 | SI07 and ((thick or thickness) with (mask or polymer)) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/22 12:39 |
| SI15 | 0 | SI07 and ((thick or thickness) with (resist)) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/22 12:39 |
| SI16 | 4 | SI07 and ((thick or thickness) with (\$resist)) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/22 12:40 |
| SI17 | 3 | SI07 and pmma | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/22 13:03 |
| SI18 | 1 | SI07 and polymethylmethacrylate | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/22 13:04 |

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|------|--------|---|---|-----|----|---------------------|
| S119 | 25 | (US-20020042027-\$ or US-20020005391-\$ or US-20030205658-\$ or US-20030205657-\$ or US-20050281982-\$ or US-20050221218-\$ or US-20040141168-\$ or US-20040124566-\$ or US-20040086793-\$ or US-20040053146-\$ or US-20040053009-\$ or US-20020168592-\$ or US-20020115002-\$ or US-20020094496-\$ or US-20060035164-\$ or US-20040170925-\$).did. or (US-5948470-\$ or US-6753130-\$ or US-4512848-\$ or US-7374968-\$ or US-7060625-\$ or US-6755984-\$ or US-6365059-\$ or US-5512131-\$).did. or (US-5948470-\$ or WO-0133300-A-\$ or DE-10030016-A-\$).did. | US-PGPUB; USPAT; DERWENT | ADJ | ON | 2008/07/22 13:07 |
| S120 | 10 | S119 and pmma | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/22 13:08 |
| S121 | 23 | S119 and nm | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/22 13:15 |
| S122 | 1 | ("20030071016").PN. | US-PGPUB; USPAT; USOCR | ADJ | ON | 2008/07/22 16:23 |
| S123 | 199 | (lee near heon).inv. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/22 16:42 |
| S124 | 15 | S123 and silicon and substrate and pattern and imprint | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/22 16:43 |
| S125 | 177981 | "430".clas. or "216".clas. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/22 16:47 |
| S126 | 533 | S125 and silicon and substrate and pattern and imprint | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/22 16:47 |

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|------|-------|--|---|-----|----|---------------------|
| SI27 | 190 | SI26 and template | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/22 16:48 |
| SI28 | 32 | SI27 and imprint pattern | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/22 16:49 |
| SI29 | 5 | 2003/0071016 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/22 16:52 |
| SI30 | 2 | "20030071016" | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/22 16:52 |
| SI31 | 456 | nano?imprint lithography | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/22 17:00 |
| SI32 | 17 | SI31 and (silicon near substrate) and (imprint pattern) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/22 17:01 |
| SI33 | 53 | "6165911" | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/22 17:05 |
| SI34 | 4 | "6673714" | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/22 17:07 |
| SI35 | 12064 | "Hewlett-Packard Development ". asn. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/23 07:32 |

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|------|--------|--|---|-----|----|---------------------|
| S136 | 53 | "6165911" | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/23 07:32 |
| S137 | 17 | S135 and S136 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/23 07:32 |
| S138 | 456 | nano?lmp rint lithography | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/23 07:33 |
| S139 | 17 | S138 and (silicon near substrate) and (imprint pattern) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/23 07:33 |
| S140 | 0 | S135 and S139 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/23 07:33 |
| S141 | 15 | S135 and S138 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/23 07:33 |
| S142 | 5 | S135 and (silicon near substrate) and (imprint pattern) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/23 07:34 |
| S143 | 202 | ingenia.asn. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/23 08:41 |
| S144 | 136401 | S143 and semiconductor or imprint or lithography | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/23 08:42 |

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|------|---------|--|---|-----|-----|---------------------|
| S145 | 12 | S143 and (semiconductor or imprint or lithography) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/23 08:42 |
| S146 | 23 | ((SHUNPU) near2 (LI)).INV. | US-PGPUB; USPAT; USOCR | ADJ | ON | 2008/07/23 09:50 |
| S147 | 32 | ((SHUNPU) near2 (LI)).INV. | EPO; JPO; DERWENT | ADJ | ON | 2008/07/23 09:51 |
| S148 | 55 | S146 or S147 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2008/07/23 09:51 |
| S149 | 22523 | (single?phase) | US-PGPUB; USPAT; USOCR | ADJ | OFF | 2009/01/05 07:18 |
| S150 | 72 | (single?phase polymer) | US-PGPUB; USPAT; USOCR | ADJ | OFF | 2009/01/05 07:18 |
| S151 | 1 | (single?phase plastic) | US-PGPUB; USPAT; USOCR | ADJ | OFF | 2009/01/05 07:19 |
| S152 | 32 | (single?phase layer) | US-PGPUB; USPAT; USOCR | ADJ | OFF | 2009/01/05 07:19 |
| S153 | 105 | S150 or S151 or S152 | US-PGPUB; USPAT; USOCR | ADJ | OFF | 2009/01/05 07:19 |
| S154 | 4559269 | @ad< "20031211" | US-PGPUB; USPAT; USOCR | ADJ | OFF | 2009/01/05 07:20 |
| S155 | 84 | S153 and S154 | US-PGPUB; USPAT; USOCR | ADJ | OFF | 2009/01/05 07:20 |
| S156 | 26 | S155 and substrate | US-PGPUB; USPAT; USOCR | ADJ | OFF | 2009/01/05 07:21 |
| S157 | 0 | S155 and template | US-PGPUB; USPAT; USOCR | ADJ | OFF | 2009/01/05 07:21 |
| S158 | 27 | shunpu.inv. | US-PGPUB; USPAT; USOCR | ADJ | OFF | 2009/01/05 07:22 |
| S159 | 60563 | (single phase) or (single-phase) | US-PGPUB; USPAT; USOCR | ADJ | OFF | 2009/01/05 07:24 |
| S160 | 219 | (single phase polymer) or (single-phase polymer) | US-PGPUB; USPAT; USOCR | ADJ | OFF | 2009/01/05 07:25 |
| S161 | 9 | (single phase plastic) or (single-phase plastic) | US-PGPUB; USPAT; USOCR | ADJ | OFF | 2009/01/05 07:25 |
| S162 | 228 | S160 or S161 | US-PGPUB; USPAT; USOCR | ADJ | OFF | 2009/01/05 07:25 |
| S163 | 65 | S162 and (template or substrate) | US-PGPUB; USPAT; USOCR | ADJ | OFF | 2009/01/05 07:25 |
| S164 | 30 | S163 and S154 | US-PGPUB; USPAT; USOCR | ADJ | OFF | 2009/01/05 07:26 |
| S165 | 0 | S164 and shunpu.inv. | US-PGPUB; USPAT; USOCR | ADJ | OFF | 2009/01/05 07:26 |
| S166 | 37 | substrate and pmmi | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/04/30 14:55 |
| S167 | 25887 | substrate and polymer and (texture or textured) | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/04/30 14:57 |

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|------|---------|---|--------------------------------|-----|----|---------------------|
| S168 | 318158 | tg or glass transition | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/04/30 14:57 |
| S169 | 7874 | below (tg or glass transition) | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/04/30 14:58 |
| S170 | 509 | S167 and S169 | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/04/30 14:58 |
| S171 | 37644 | polymer layer | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/04/30 14:59 |
| S172 | 122 | S170 and S171 | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/04/30 14:59 |
| S173 | 25 | (US-20020042027-\$ or US-20020005391-\$ or US-20030205658-\$ or US-20030205657-\$ or US-20050281982-\$ or US-20050221218-\$ or US-20040141168-\$ or US-20040124566-\$ or US-20040086793-\$ or US-20040053146-\$ or US-20040053009-\$ or US-20020168592-\$ or US-20020115002-\$ or US-20020094496-\$ or US-20060035164-\$ or US-20040170925-\$).did. or (US-5948470-\$ or US-6753130-\$ or US-4512848-\$ or US-7374968-\$ or US-7060625-\$ or US-6755984-\$ or US-6365059-\$ or US-5512131-\$).did. or (US-5948470-\$ or WO-0133300-A-\$ or DE-10030016-A-\$).did. | US-PGPUB; USPAT; DERWENT | ADJ | ON | 2009/04/30 15:14 |
| S174 | 1 | S173 and S169 | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/04/30 15:15 |
| S175 | 6 | S173 and S168 | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/04/30 15:15 |
| S176 | 245154 | "428".clas. | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/04/30 15:19 |
| S177 | 55 | S172 and S176 | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/04/30 15:19 |
| S178 | 0 | ("2005/0281982").URPN. | USPAT | ADJ | ON | 2009/04/30 15:30 |
| S179 | 2110815 | template or stamp or stamper or press or die or mold | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/04/30 15:31 |
| S180 | 2589840 | layer or substrate | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/04/30 15:31 |
| S181 | 1012394 | polymer | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/04/30 15:31 |
| S182 | 324457 | S179 and S180 and S181 | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/04/30 15:31 |
| S183 | 3298 | S182 and S169 | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/04/30 15:33 |
| S184 | 451 | S183 and S171 | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/04/30 15:34 |
| S185 | 3 | S184 and "249".clas. | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/04/30 15:36 |

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|------|--------|--|---------------------------|-----|----|---------------------|
| S186 | 91799 | germanium | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/01 08:57 |
| S187 | 35821 | pmma | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/01 08:57 |
| S188 | 1731 | S186 and S187 | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/01 08:57 |
| S189 | 48253 | germanium and semiconductor and substrate | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/01 08:58 |
| S190 | 1098 | S188 and S189 | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/01 08:58 |
| S191 | 83956 | texture and (bake or baking or heat or heating or heated) | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/01 08:58 |
| S192 | 63 | S190 and S191 | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/01 08:58 |
| S193 | 0 | master and resist and germanium and (@ay<"2003" or @prad<"20030101" or @py<"2003") | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/01 09:36 |
| S194 | 0 | master and resist and germanium | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/01 09:36 |
| S195 | 2760 | master and germanium | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/01 09:37 |
| S196 | 734 | S195 and resist | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/01 09:37 |
| S197 | 393 | S196 and (@ay<"2003" or @prad<"20030101" or @py<"2003") | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/01 09:37 |
| S198 | 73 | S197 and pmma | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/01 09:37 |
| S199 | 67 | S198 and (heat or temperature or bake or heated or baked) | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/01 09:38 |
| S200 | 67 | S199 and substrate | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/01 09:39 |
| S201 | 1 | S199 and pmma layer | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/01 09:39 |
| S202 | 6 | ("4098917" "4127414" "4188215" "4256825" "4269935" "4276368").PN. | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/01 09:40 |
| S203 | 18 | ("4373018").URFN. | USPAT | ADJ | ON | 2009/05/01 09:41 |
| S204 | 109 | 977/887.ccls. | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/05 10:47 |
| S205 | 156504 | substrate and (anneal or anneal\$) | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/05 10:48 |
| S206 | 5 | S204 and S205 | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/05 10:48 |
| S207 | 2619 | S205 and pmma | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/05 10:56 |
| S208 | 20706 | S205 and germanium | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/05 10:57 |
| S209 | 2784 | germanium near substrate | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/05 10:57 |

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|------|---------|--|---------------------------|-----|-----|---------------------|
| S210 | 1274 | S208 and S209 | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/05 10:57 |
| S211 | 3530331 | (heat or temperature or bake or heated or baked) | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/05 10:58 |
| S212 | 1189 | S210 and S211 | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/05 10:58 |
| S213 | 154 | S212 and polymer | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/05 10:59 |
| S214 | 266679 | textu\$ | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/05 11:00 |
| S215 | 170767 | texture | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/05 11:00 |
| S216 | 10 | S213 and S214 | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/05 11:00 |
| S218 | 1850800 | template or imprint or stamp or press or mask | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/05 11:03 |
| S219 | 130 | S213 and S218 | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/05 11:03 |
| S220 | 5079 | S208 and polymer | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/05 12:03 |
| S221 | 373 | S220 and polymer layer | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/05 12:03 |
| S222 | 144062 | S205 and S211 | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/05 13:03 |
| S223 | 2820 | S222 and polymer layer | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/05 13:03 |
| S224 | 362 | S223 and germanium | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/05 13:03 |
| S225 | 1488 | 425/385.ccls. | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/05 14:37 |
| S226 | 10 | S225 and germanium | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/05 14:37 |
| S227 | 20 | S225 and anneal\$ | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/05 14:40 |
| S228 | 32 | ("20020185584" "20030080458" "20030209819" "20040029041" "20040036201" "20040039090" "20040131718" "20040146792" "20040169861" "20040233442" "20040233443" "20040233444" "20040259279" "20050067379" "20050133954" "20050179149" "20060183060" "5204126" "6429932" "6517995" "6607173" "6632342" "6656393" "6713238" "6921630" "6936181" "6949199" "7013064" "7070405" "7077992" "7136150" "7235474").PN. | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/05 14:52 |
| S229 | 4622 | ((425/171) or (425/174) or (425/174.4) or (264/1.38) or (425/385) or (425/169) or (425/173)).CCLS. | US-PGPUB; USPAT; USOCR | OR | OFF | 2009/05/12 10:03 |

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|------|--------|--|------------------------|-----|-----|------------------|
| S230 | 97200 | pmgi or polymethylgluta\$ or poly methyl glutar\$ or polymethyl glutar \$ or poly methylglutar\$ or pmma or poly methyl methacrylate or poly methylmethacrylate or polymethyl methacrylate or polymethylmethacrylate or (photoresist (az-5214\$ or az5214\$ or az "5214"\$ or az-5214 or az "5214" or az5214)) | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 10:27 |
| S231 | 92066 | germanium | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 10:27 |
| S232 | 7 | S229 and S230 and S231 | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 10:27 |
| S233 | 241280 | anneal or anneal\$ | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 12:25 |
| S234 | 4622 | ((425/171) or (425/174) or (425/174.4) or (264/1.38) or (425/385) or (425/169) or (425/173)).CQLS. | US-PGPUB; USPAT; USOCR | OR | OFF | 2009/05/12 12:25 |
| S235 | 97200 | pmgi or polymethylgluta\$ or poly methyl glutar\$ or polymethyl glutar \$ or poly methylglutar\$ or pmma or poly methyl methacrylate or poly methylmethacrylate or polymethyl methacrylate or polymethylmethacrylate or (photoresist (az-5214\$ or az5214\$ or az "5214"\$ or az-5214 or az "5214" or az5214)) | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 12:26 |
| S236 | 24 | S233 and S234 and S235 | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 12:26 |
| S237 | 156837 | S233 and substrate | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 12:42 |
| S238 | 49764 | S237 and (mold or template or stamp or stamper) | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 13:02 |
| S239 | 2676 | S238 and S235 | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 13:02 |
| S240 | 13 | S239 and S234 | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 13:02 |
| S241 | 8129 | S233 near (polymer or plastic or template or semiconductor or mold) | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 14:30 |
| S242 | 275 | S241 and ("264". clas. or "425". clas.) | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 14:30 |
| S243 | 0 | (2002/0042027).CQLS. | US-PGPUB; USPAT; USOCR | OR | OFF | 2009/05/12 14:44 |
| S244 | 58 | 2002/0042027 | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 14:44 |
| S245 | 0 | 2002/0042027.pn. | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 14:46 |
| S246 | 541 | "5772905" | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 15:01 |
| S247 | 1 | "5772905".pn. | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 15:01 |

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|------|--------|---|---------------------------|-----|----|---------------------|
| S248 | 1 | "6849558".pn. | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 16:24 |
| S249 | 1 | "6755984".pn. | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 16:26 |
| S250 | 103562 | "10 nm" or "10nm" | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 16:33 |
| S251 | 3552 | S250 near (substrate or layer or semiconductor or germanium or silicon or wafer) | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 16:33 |
| S252 | 40 | S251 and chou | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 16:34 |
| S253 | 131 | "5259926" | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 16:37 |
| S254 | 940 | S250 near (substrate or semiconductor or germanium or silicon or wafer) | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 16:44 |
| S255 | 332 | S250 near substrate | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 16:44 |
| S256 | 65 | S250 near semiconductor | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 16:45 |
| S257 | 1199 | S250 and ("264".clas. or "425". clas.) | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 16:49 |
| S258 | 1076 | S257 and (substrate or layer or semiconductor) | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 16:50 |
| S259 | 780 | S258 and substrate | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 16:50 |
| S260 | 718 | S259 and layer | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 16:50 |
| S261 | 280 | S260 and semiconductor | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 16:50 |
| S262 | 79 | S261 and chou | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 16:50 |
| S263 | 5468 | ("10 nm" or "10nm") with semiconductor | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 16:52 |
| S264 | 2526 | ("10 nm" or "10nm") with semiconductor with layer | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 16:52 |
| S265 | 8 | S264 and chou | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 16:52 |
| S266 | 135 | "6323108" | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/13 14:09 |
| S267 | 13 | ("5013681" "5024723" "5303255" "5374564" "5540785" "5646058" "5681775" "5757038" "5877070" "5882987" "5953620" "5980633" "6004865").PN. | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/13 14:39 |
| S268 | 6 | "588297".PN. | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/13 14:42 |
| S269 | 46 | "4771016" | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/13 14:46 |
| S270 | 103562 | ("10 nm" or "10nm") | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/13 14:47 |

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|------|---|---------------|---------------------------|-----|----|---------------------|
| S271 | 6 | S269 and S270 | US-PGPUB; USPAT: USOCR | ADJ | ON | 2009/05/13 14:47 |
| S272 | 5 | "6030556" | US-PGPUB; USPAT: USOCR | ADJ | ON | 2009/05/13 15:01 |

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